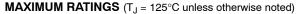
Preferred Device

Dual Common Cathode Schottky Barrier Diodes

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand-held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Low Forward Voltage 0.35 V (Typ) @ $I_F = 10 \text{ mAdc}$
- Pb-Free Package is Available



Rating	Symbol	Symbol Value	
Reverse Voltage	V _R	30	V
Forward Power Dissipation @ T _A = 25°C Derate above 25°C	P _F	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	508 (Note 1) 311 (Note 2)	°C/W
Forward Current (DC)	IF	200 Max	mA
Junction Temperature	TJ	-55 to +125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

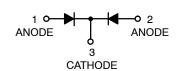
- 1. FR-4 @ Minimum Pad.
- 2. FR-4 @ 1.0 x 1.0 inch Pad.

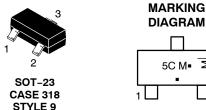


ON Semiconductor®

http://onsemi.com

30 VOLT **DUAL COMMON CATHODE** SCHOTTKY BARRIER DIODES





5C = Device Code М = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

5C M■ ≥

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

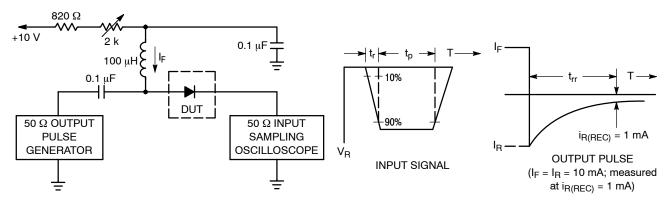
Device	Package	Shipping [†]
BAT54CLT1	SOT-23	3000/Tape & Reel
BAT54CLT1G	SOT-23 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

$\textbf{ELECTRICAL CHARACTERISTICS} \ (T_{A} = 25^{\circ}\text{C unless otherwise noted}) \ (\text{EACH DIODE})$

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I _R = 10 μA)	V _{(BR)R}	30	-	-	V
Total Capacitance (V _R = 1.0 V, f = 1.0 MHz)	C _T	-	7.6	10	pF
Reverse Leakage (V _R = 25 V)	I _R	-	0.5	2.0	μAdc
Forward Voltage (I _F = 0.1 mAdc)	V _F	-	0.22	0.24	Vdc
Forward Voltage (I _F = 30 mAdc)	V _F	-	0.41	0.5	Vdc
Forward Voltage (I _F = 100 mAdc)	V _F	-	0.52	0.8	Vdc
Reverse Recovery Time $(I_F = I_R = 10 \text{ mAdc}, I_{R(REC)} = 1.0 \text{ mAdc}, Figure 1)$	t _{rr}	-	_	5.0	ns
Forward Voltage (I _F = 1.0 mAdc)	V _F	_	0.29	0.32	Vdc
Forward Voltage (I _F = 10 mAdc)	V _F	-	0.35	0.40	Vdc
Forward Current (DC)	I _F	-	-	200	mAdc
Repetitive Peak Forward Current	I _{FRM}	-	-	300	mAdc
Non-Repetitive Peak Forward Current (t < 1.0 s)	I _{FSM}	-	-	600	mAdc



Notes: 1. A 2.0 $k\Omega$ variable resistor adjusted for a Forward Current (I_F) of 10 mA.

- 2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.
- 3. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

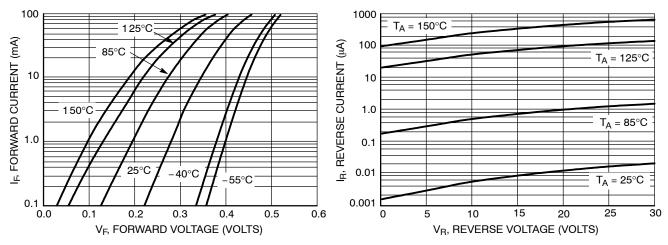


Figure 2. Forward Voltage

Figure 3. Leakage Current

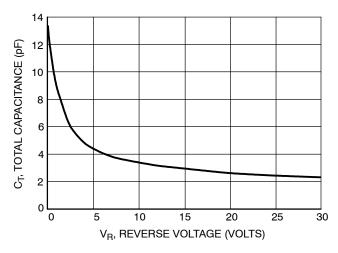
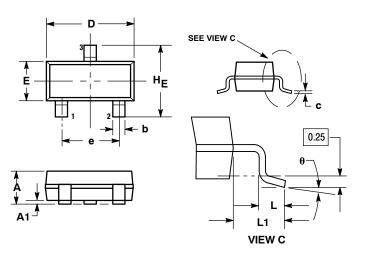


Figure 4. Total Capacitance

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN**



- DIMENSIONING AND TOLERANCING PER ANSI
- DIMENSIONING AND TOLEHANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

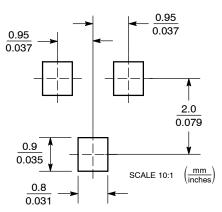
	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.89	1.00	1.11	0.035	0.040	0.044	
A1	0.01	0.06	0.10	0.001	0.002	0.004	
b	0.37	0.44	0.50	0.015	0.018	0.020	
С	0.09	0.13	0.18	0.003	0.005	0.007	
D	2.80	2.90	3.04	0.110	0.114	0.120	
E	1.20	1.30	1.40	0.047	0.051	0.055	
е	1.78	1.90	2.04	0.070	0.075	0.081	
L	0.10	0.20	0.30	0.004	0.008	0.012	
L1	0.35	0.54	0.69	0.014	0.021	0.029	
HE	2.10	2.40	2.64	0.083	0.094	0.104	

STYLE 9:

- PIN 1. ANODE 2. ANODE

 - CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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